

■ Features

- This filter is characterized by small size, highly effective in noise suppression.
- High common mode impedance at noise band and low differential mode impedance at signal band. Due to the low differential mode impedance with high coupling factor, there is almost no distortion on high speed transmission of high resolution video signals.

■ Applications

- YLM Series is suited for use on the USB2.0 line and IEEE1394 line of Notebook PC, LVDS lines of PC, LCD Monitor, PCI express, small digital AV equipment such as digital Camera and Free disk, MP3 player and Serial-ATA.

■ Product Identification

$$\frac{\text{YLM}}{(1)} \quad \frac{\square\square\square\square}{(2)} - \frac{\square\square\square}{(3)} \quad \frac{\text{T}}{(4)}$$

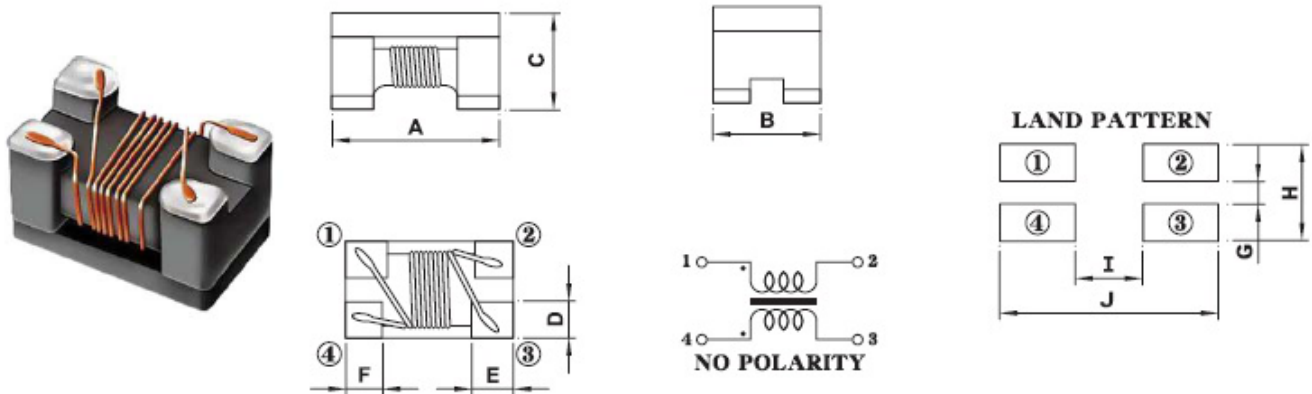
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Taping

Shapes and Dimensions (Unit: mm)

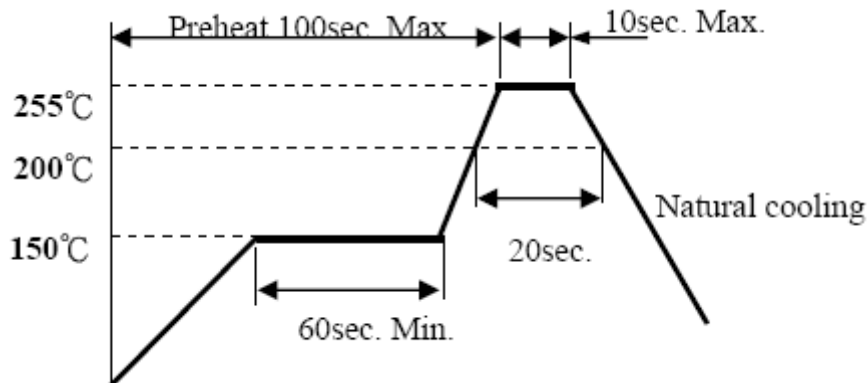


TYPE	A	B	C	D	E	F	G	H	I	J
YLM2012	2.0±0.2	1.2±0.2	1.2±0.2	0.50±0.1	0.50±0.1	0.50±0.1	0.40	1.20	0.80	2.60

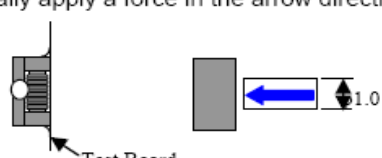
YLM2012 Series

Part Number	Common mode Impedance (Ω) @100MHz	DC Resistance (Ω) Max	Rated Current (mA) max	Rated Volt. (Vdc)max.	Withstand Volt.(Vdc)max.	IR(MΩ) min.
YLM2012-300T	30±25%	0.20	450	50	125	10
YLM2012-670T	67±25%	0.25	400	50	125	10
YLM2012-900T	90±25%	0.30	400	50	125	10
YLM2012-121T	120±25%	0.30	400	50	125	10
YLM2012-161T	160±25%	0.35	350	50	125	10
YLM2012-181T	180±25%	0.35	350	50	125	10
YLM2012-201T	200±25%	0.40	300	50	125	10
YLM2012-221T	220±25%	0.40	300	50	125	10
YLM2012-261T	260±25%	0.40	300	50	125	10
YLM2012-361T	360±25%	0.50	300	50	125	10
YLM2012-601T	600±25%	0.88	300	50	125	10
YLM2012-751T	750±25%	1.00	180	50	125	10
YLM2012-901T	900±25%	1.15	150	50	125	10
YLM2012-102T	1000±25%	1.30	100	50	125	10

Recommended soldering temp.Graph



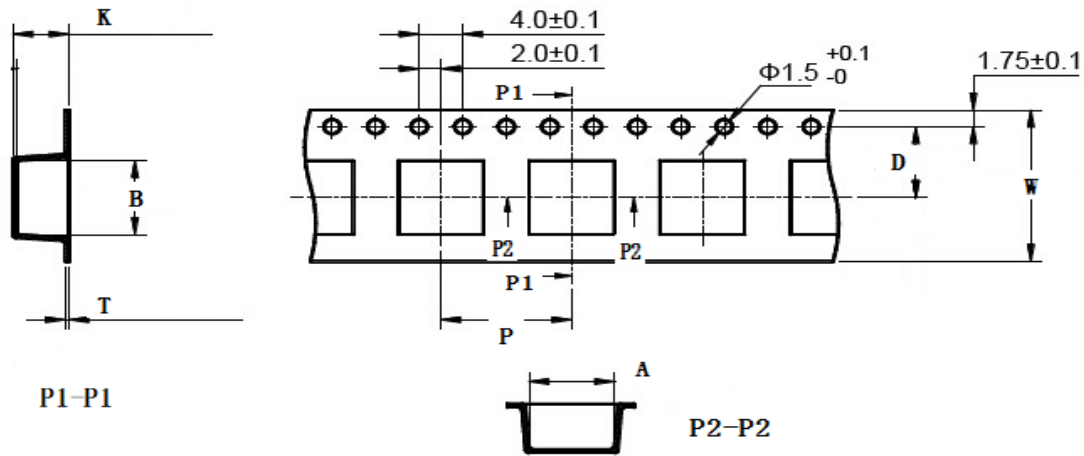
Mechanical reliability

TEST	Specification & Requirement		Method Used
Solderability	The surface of terminal/pin tested shall be covered with new solder by 90%		Solder heat proof: Preheating: 150 ±10°C 60 seconds Soldering: 230 ±5°C for 3 ±1 sec
Solder Heat Resistance	Components should have not evidence of electrical and mechanical damage Impedance: within ±15% of initial value		Preheating: 150°C 60secs Solder temperature: 260±5°C Flux: rosin Dip time: 10±0.5 secs
Terminal strength	Series No.	F (Kg)	Solder a chip to test substrate and then laterally apply a force in the arrow direction 
	YLM2012	0.5	
	YLM3216/3225	1.0	
	YLM4532	1.5	

Endurance Reliability

TEST	Specification & Requirement	Method Used
Thermal Shock	Impedance change within ± 15% Without mechanical damage	-25°C, (30 mins) -> room temp. (5 mins) -> 125°C, (30 mins) -> room temp. (5 mins) 10 cycles
Humidity Resistance	Impedance change within ± 15% Without mechanical damage	Apply IDC current @ 60°C ambient Humidity: 80% Duration: 168 hrs
Low Temp. Storing	Impedance change within ± 15% Without mechanical damage	Storing Temp. -25 ±2 °C for total 168 +5/-0 hours
High Temp. Storing	Impedance change within ± 15% Without mechanical damage	Storing Temp. 125 ±2 °C for total 168 +5/-0 hours

■ Taping Dimensions(Unit:mm)



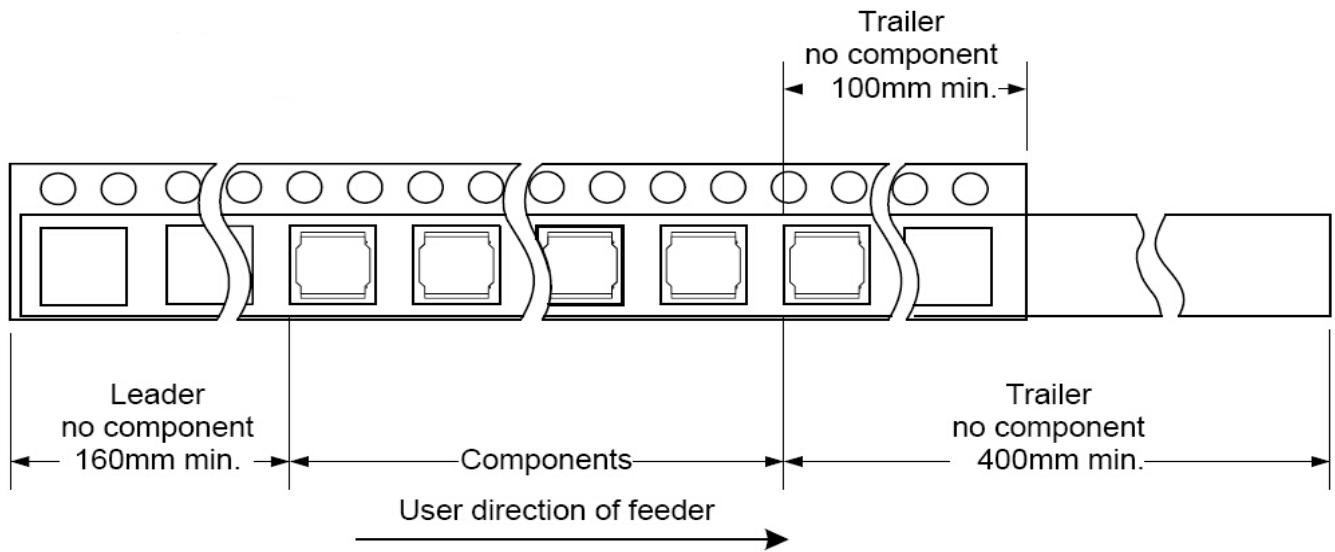
TYPE	W	A	B	D	P	K	T	MPQ
YLM2012	8.0±0.2	1.50±0.1	2.35±0.1	3.5±0.05	4.0±0.1	1.45±0.1	0.26±0.05	2000

■ Reel Dimensions(Unit:mm)



TYPE	W	W1	A	B	C	D
YLM2012	178±2.0	9.00±0.50	4.3±0.20	5.0±0.10	3.0±0.10	60±2.0

Direction of rolling



Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.